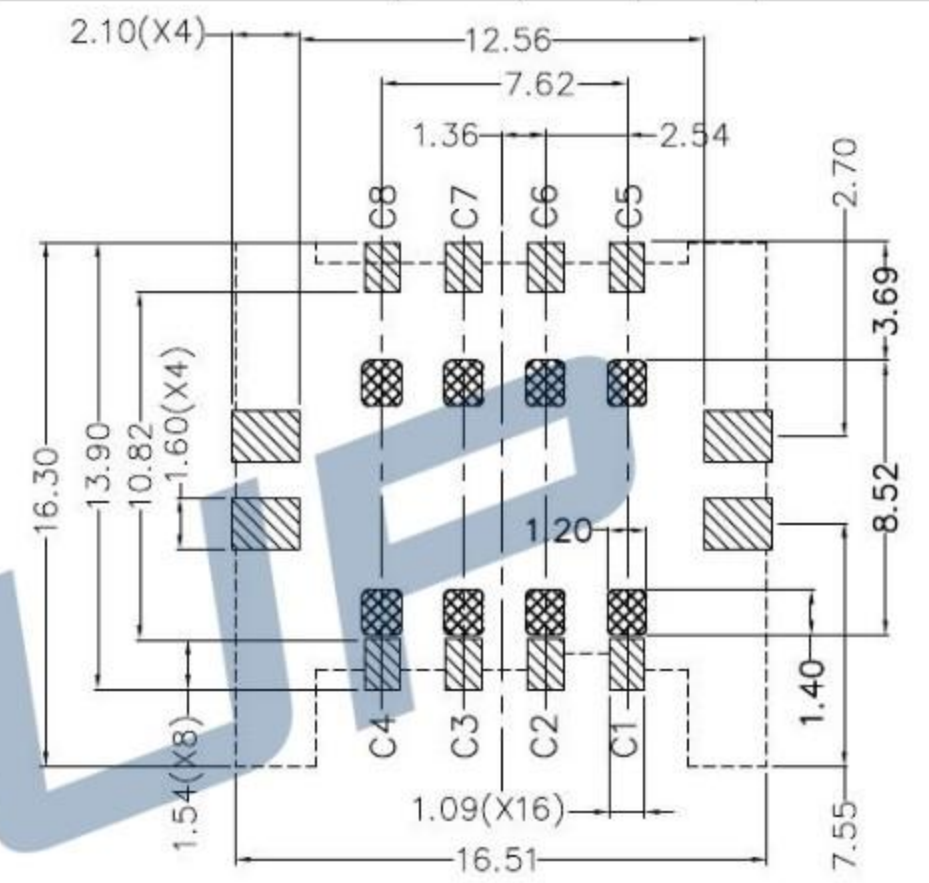
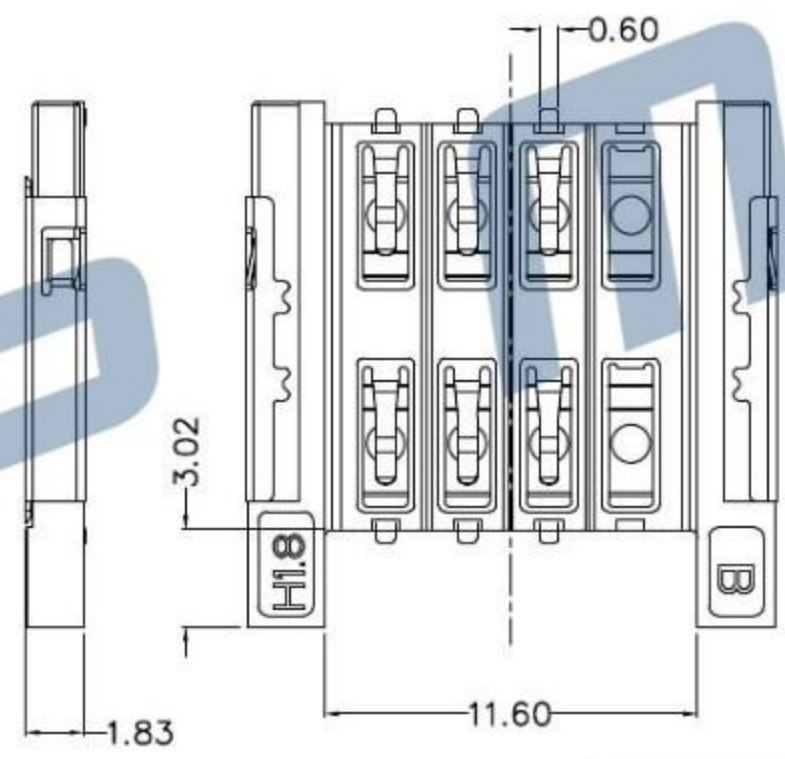
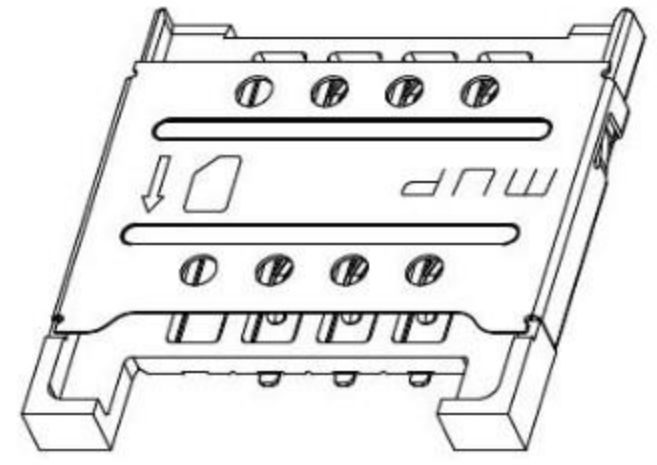
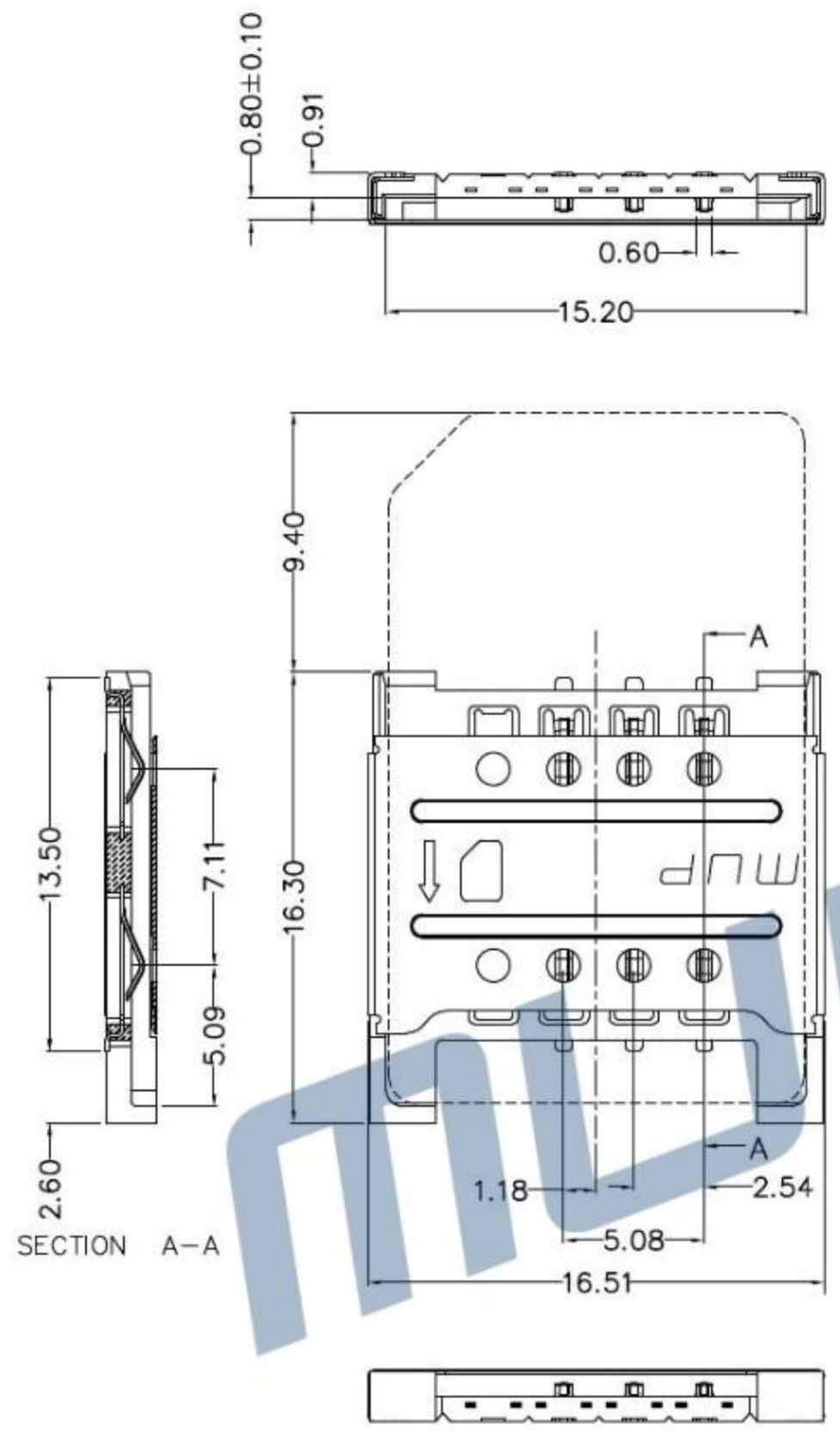


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1					



RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)

- PAD AREA
- KEEP AREA

TECHNICAL CHARACTERISTICS

1.General Characteristics
 Dimensions: 16.51LX16.30WX1.80H mm
 Weight: Approx g
 Durability: 5,000 cycles min.

2.Electrical Characteristics
 Contact resistance: 50mΩ typical, 100mΩ max
 Insulation resistance: >1000MΩ/500V DC

3.Solderability
 Vaporphase: 215°C, 30sec. Max
 IR reflow: 250°C, 5sec. Max
 Manual soldering: 370°C, 3sec. Max

4.Environmental Characteristics
 Operating temperature: -40°C~+85°C
 Operating humidity: 10%~+95%RH

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	6	Copper Alloy	Contact area: Gold plated
3	SHELL	1	Stainless Steel	SMT area: Gold plated

Unless otherwise specified, other tolerance are:

X	±0.35	X'	±5'
X.X	±0.25	X.X'	±4'
X.XX	±0.15	X.XX'	±3'
X.XXX	±0.10	X.XXX'	±2'

MUP MUP INDUSTRIAL CO.,LTD.

NAME: **SIM Card Connector**

MODEL NO: **MUP C708-5**

TYPE: **H1.80 Without post 6P**

PROJ.	UNIT	SCALE	DRAWN	Jimmy 5/10-17'	DWG NO.:
	mm	1:1	CHECKED	Sean 5/10-17'	DWG-MUP-C708-005
CUSTOMER DRAWING			APPROVAL	Simon 5/10-17'	SHEET
					1/1
					REVISION
					X1

